



# FDB14N30

## N-Channel UniFET™ MOSFET

300 V, 14 A, 290 mΩ

### Features

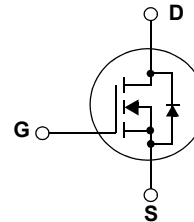
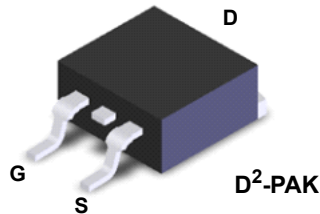
- $R_{DS(on)} = 290\text{ m}\Omega$  (Max.) @  $V_{GS} = 10\text{ V}$ ,  $I_D = 7\text{ A}$
- Low Gate Charge (Typ. 18 nC)
- Low  $C_{rss}$  (Typ. 17 pF)
- 100% Avalanche Tested
- Improved dv/dt Capability

### Applications

- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

### Description

UniFET™ MOSFET is Fairchild Semiconductor®'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



### Absolute Maximum Ratings

| Symbol         | Parameter  |  | FDB14N30    | Unit                |
|----------------|--|--|-------------|---------------------|
| $V_{DSS}$      | Drain-Source Voltage   |  | 300         | V                   |
| $I_D$          | Drain Current  | - Continuous ( $T_C = 25^\circ\text{C}$ )  | 14          | A                   |
|                |  | - Continuous ( $T_C = 100^\circ\text{C}$ ) | 8.4         | A                   |
| $I_{DM}$       | Drain Current  | - Pulsed (Note 1)                          | 56          | A                   |
| $V_{GSS}$      | Gate-Source voltage  |  | $\pm 30$    | V                   |
| $E_{AS}$       | Single Pulsed Avalanche Energy   | (Note 2)                                   | 330         | mJ                  |
| $I_{AR}$       | Avalanche Current  | (Note 1)                                   | 14          | A                   |
| $E_{AR}$       | Repetitive Avalanche Energy  | (Note 1)                                   | 14          | mJ                  |
| dv/dt          | Peak Diode Recovery dv/dt  | (Note 3)                                   | 4.5         | V/ns                |
| $P_D$          | Power Dissipation  | ( $T_C = 25^\circ\text{C}$ )               | 140         | W                   |
|                |  | - Derate above $25^\circ\text{C}$          | 1.12        | W/ $^\circ\text{C}$ |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                                      |  | -55 to +150 | $^\circ\text{C}$    |
| $T_L$          | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds |  | 300         | $^\circ\text{C}$    |

### Thermal Characteristics

| Symbol          | Parameter                                     | FDB14N30 | Unit                      |
|-----------------|---|----------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max.    | 0.89     | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 62.5     | $^\circ\text{C}/\text{W}$ |

## Package Marking and Ordering Information

| Device Marking | Device     | Package | Reel Size | Tape Width | Quantity |
|----------------|------------|---------|-----------|------------|----------|
| FDB14N30       | FDB14N30TM | D2-PAK  | 330mm     | 24mm       | 800      |

## Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

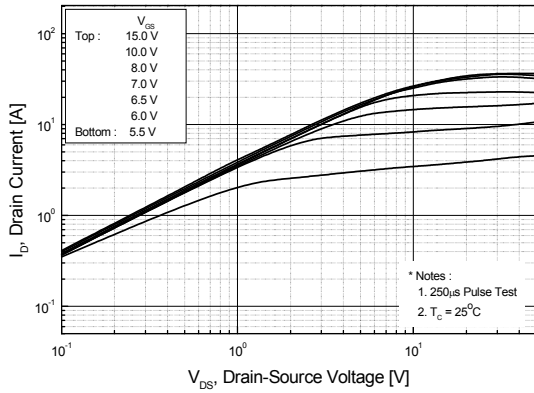
| Symbol  | Parameter   | Conditions   | Min.     | Typ. | Max     | Unit     |
|---|---|--|----------|------|---------|----------|
| <b>Off Characteristics</b>                                    |   |  |          |      |         |          |
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                        | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA   | 300      | --   | --      | V        |
| ΔBV <sub>DSS</sub><br>/ ΔT <sub>J</sub>                       | Breakdown Voltage Temperature Coefficient             | I <sub>D</sub> = 250μA, Referenced to 25°C   | --       | 0.3  | --      | V/°C     |
| I <sub>DSS</sub>  | Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = 300V, V <sub>GS</sub> = 0V<br>V <sub>DS</sub> = 240V, T <sub>C</sub> = 125°C | --       | --   | 1<br>10 | μA<br>μA |
| I <sub>GSSF</sub>   | Gate-Body Leakage Current, Forward                    | V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V  | --       | --   | 100     | nA       |
| I <sub>GSSR</sub>   | Gate-Body Leakage Current, Reverse                    | V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V   | --       | --   | -100    | nA       |
| <b>On Characteristics</b>                                     |   |  |          |      |         |          |
| V <sub>GS(th)</sub>   | Gate Threshold Voltage                                | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                                     | 3.0      | --   | 5.0     | V        |
| R <sub>DS(on)</sub>   | Static Drain-Source On-Resistance                     | V <sub>GS</sub> = 10V, I <sub>D</sub> = 7A   | --       | 0.24 | 0.29    | Ω        |
| g <sub>FS</sub>   | Forward Transconductance                              | V <sub>DS</sub> = 40V, I <sub>D</sub> = 7A   | --       | 10.5 | --      | S        |
| <b>Dynamic Characteristics</b>                                |   |  |          |      |         |          |
| C <sub>iss</sub>  | Input Capacitance                                     | V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V,<br>f = 1.0MHz                                     | --       | 815  | 1060    | pF       |
| C <sub>oss</sub>  | Output Capacitance                                    |  | --       | 150  | 195     | pF       |
| C <sub>rss</sub>  | Reverse Transfer Capacitance                          |  | --       | 17   | 25      | pF       |
| <b>Switching Characteristics</b>                              |   |  |          |      |         |          |
| t <sub>d(on)</sub>  | Turn-On Delay Time                                    | V <sub>DD</sub> = 150V, I <sub>D</sub> = 14A<br>R <sub>G</sub> = 25Ω                           | --       | 20   | 50      | ns       |
| t <sub>r</sub>  | Turn-On Rise Time                                     |  | --       | 105  | 120     | ns       |
| t <sub>d(off)</sub>   | Turn-Off Delay Time                                   |  | --       | 30   | 70      | ns       |
| t <sub>f</sub>  | Turn-Off Fall Time                                    |  | (Note 4) | --   | 75      | 160      |
| Q <sub>g</sub>  | Total Gate Charge                                     | V <sub>DS</sub> = 240V, I <sub>D</sub> = 14A<br>V <sub>GS</sub> = 10V                          | --       | 18   | 25      | nC       |
| Q <sub>gs</sub>   | Gate-Source Charge                                    |  | --       | 4.5  | --      | nC       |
| Q <sub>gd</sub>   | Gate-Drain Charge                                     |  | (Note 4) | --   | 8       | --       |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |   |  |          |      |         |          |
| I <sub>S</sub>  | Maximum Continuous Drain-Source Diode Forward Current |  | --       | --   | 14      | A        |
| I <sub>SM</sub>   | Maximum Pulsed Drain-Source Diode Forward Current     |  | --       | --   | 56      | A        |
| V <sub>SD</sub>   | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0V, I <sub>S</sub> = 14A   | --       | --   | 1.4     | V        |
| t <sub>rr</sub>   | Reverse Recovery Time                                 | V <sub>GS</sub> = 0V, I <sub>S</sub> = 14A<br>di <sub>F</sub> /dt = 100A/μs                    | --       | 235  | --      | ns       |
| Q <sub>rr</sub>   | Reverse Recovery Charge                               |  | --       | 1.6  | --      | μC       |

### NOTES:

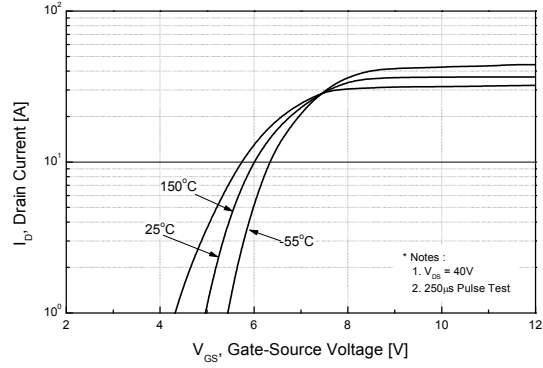
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 2.8mH, I<sub>AS</sub> = 14A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C
3. I<sub>SD</sub> ≤ 14A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

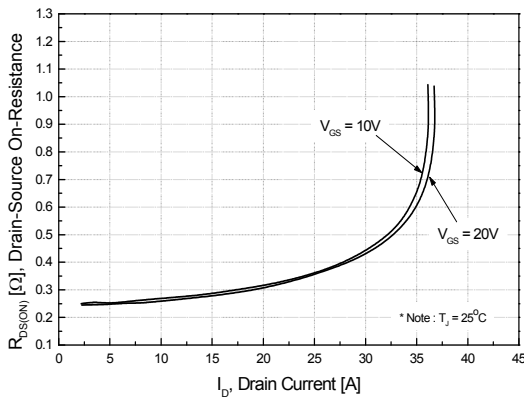
**Figure 1. On-Region Characteristics**



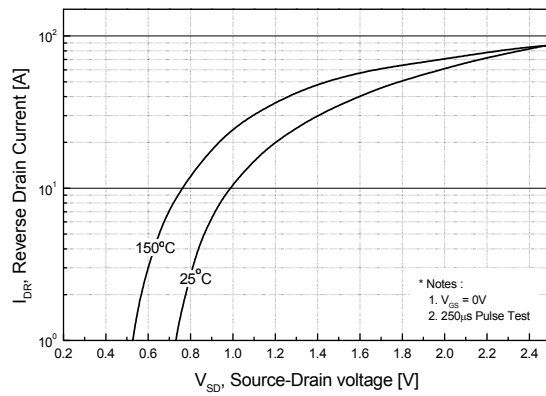
**Figure 2. Transfer Characteristics**



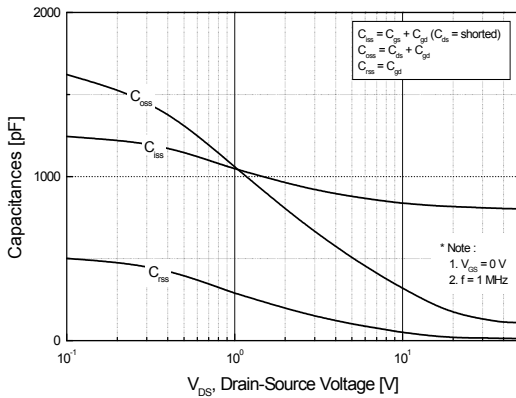
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



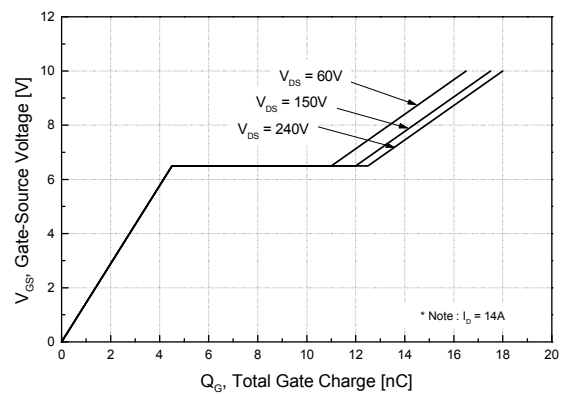
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

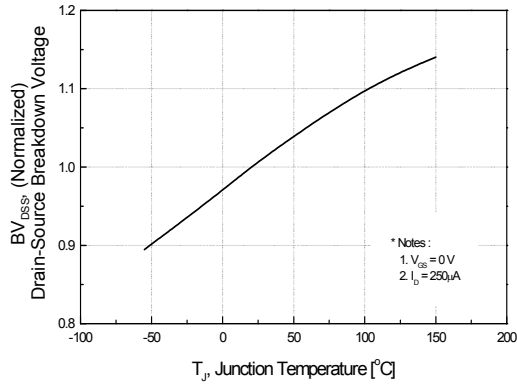


**Figure 6. Gate Charge Characteristics**

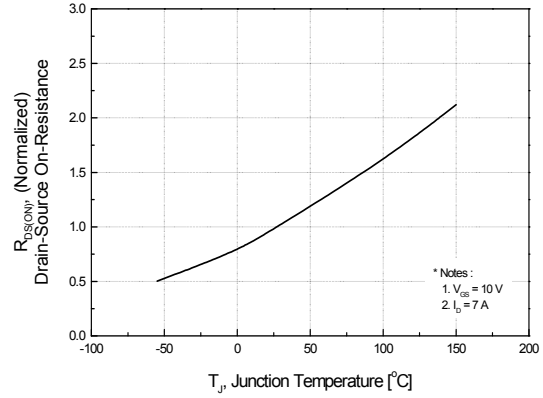


**Typical Performance Characteristics** (Continued)

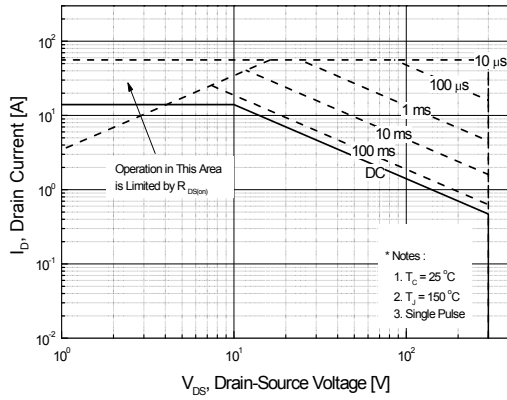
**Figure 7. Breakdown Voltage Variation vs. Temperature**



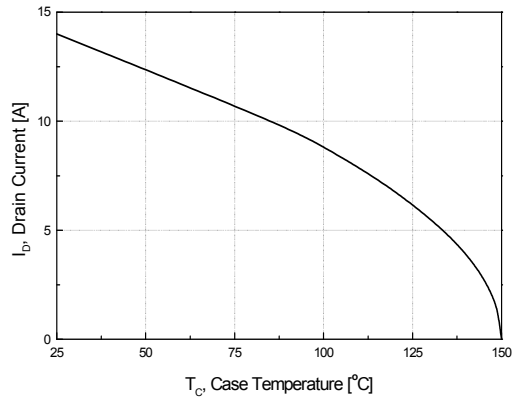
**Figure 8. On-Resistance Variation vs. Temperature**



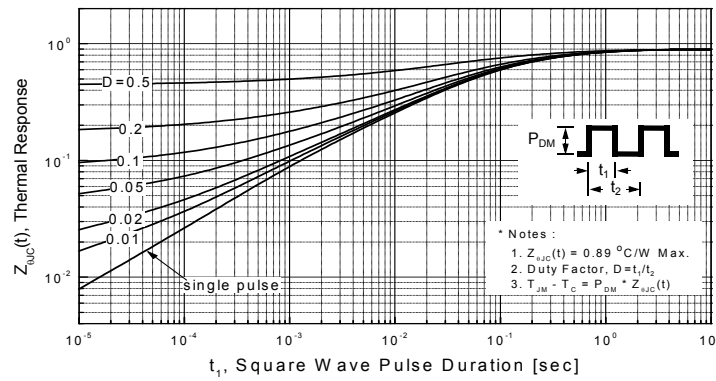
**Figure 9. Maximum Safe Operating Area**



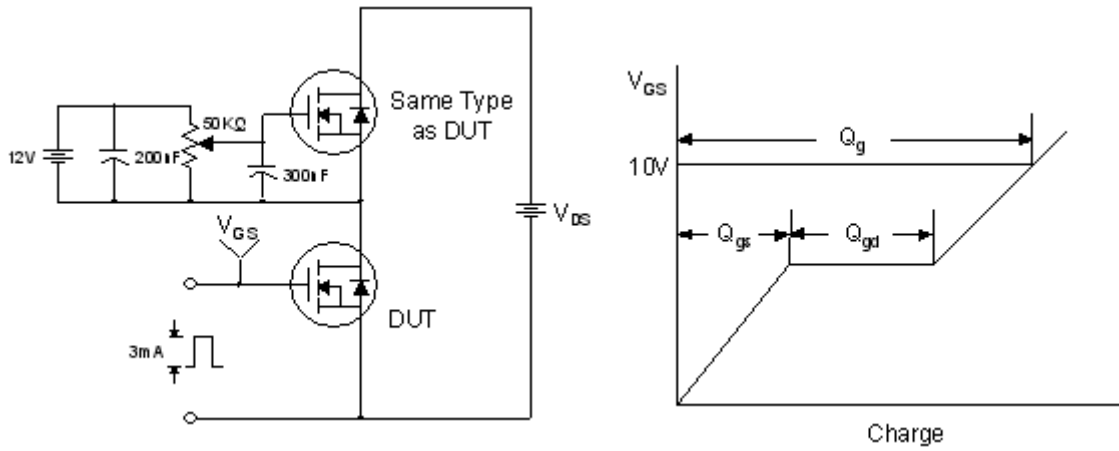
**Figure 10. Maximum Drain Current vs. Case Temperature**



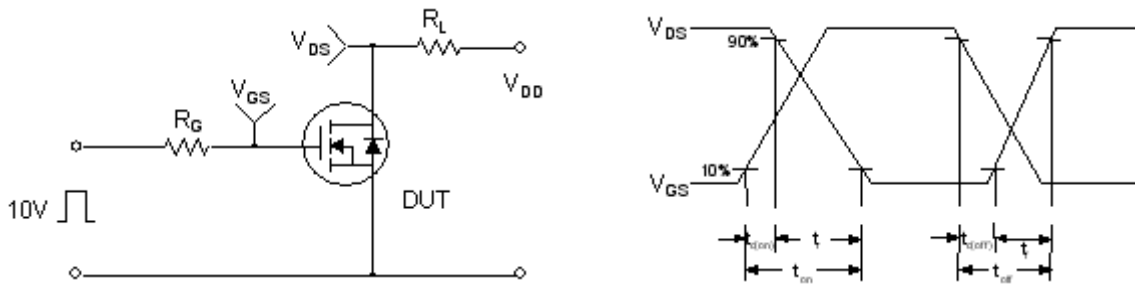
**Figure 11. Transient Thermal Response Curve**



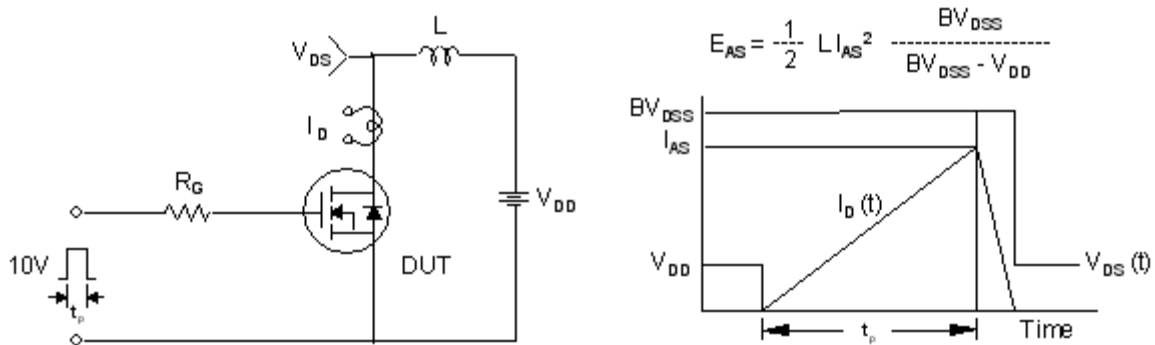
**Gate Charge Test Circuit & Waveform**



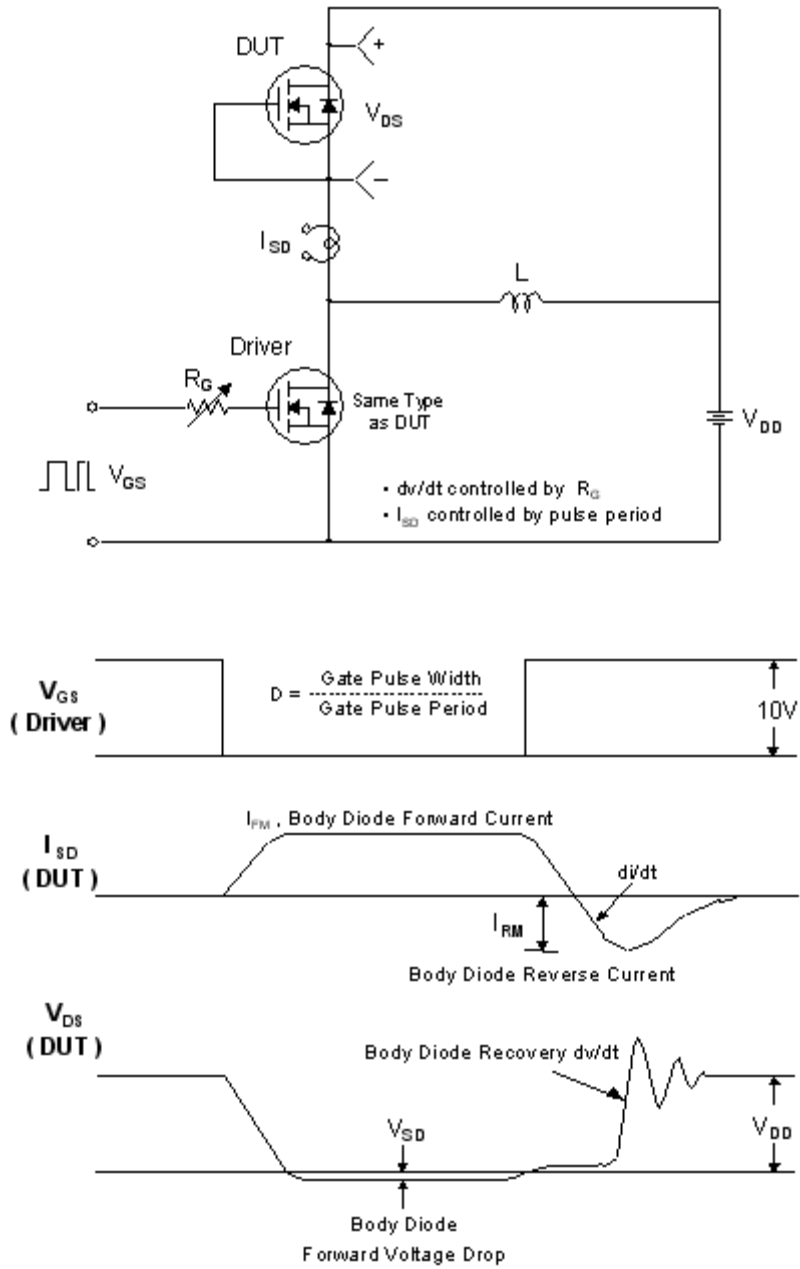
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

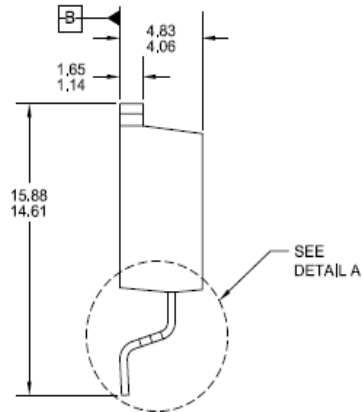
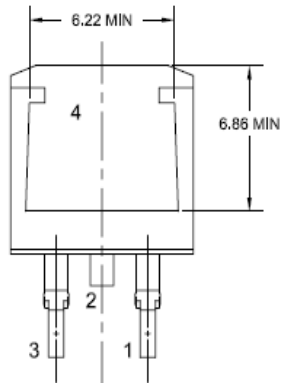
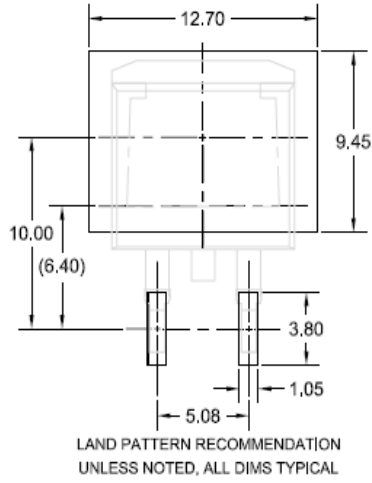
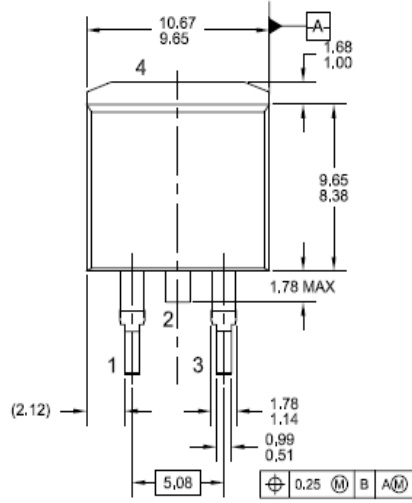


**Peak Diode Recovery dv/dt Test Circuit & Waveforms**

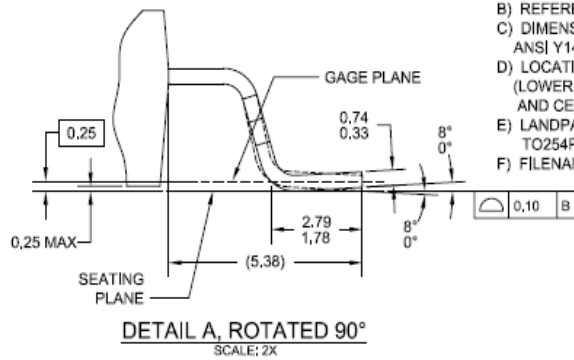


**Mechanical Dimensions**

**D<sup>2</sup>PAK**



- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) ALL DIMENSIONS ARE IN MILLIMETERS.  
 B) REFERENCE JEDEC, TO-263, VARIATION AB.  
 C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.  
 D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).  
 E) LANDPATTERN RECOMMENDATION PER IPC TO254P1524X482-3N  
 F) FILENAME: TO263A02REV6



Dimensions in Millimeters



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- |                          |   |                            |                          |
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| AccuPower™               | F-PFST™   | PowerXS™                   | <b>SYSTEM GENERAL</b> ®* |
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| BitSiC™                  | Global Power Resource <sup>SM</sup>             | QFET®                      | TinyBuck™                |
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| EfficientMax™            | MICROCOUPLER™                                   | ™                          | µSerDes™                 |
| ESBC™                    | MicroFET™                                       | ™                          | <b>µSerDes™</b>          |
| <b>F</b> ®               | MicroPak™                                       | ™                          | UHC®                     |
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